



## Product Change Notification / LIAL-14KZIS105

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### Date:

04-Jul-2023

### Product Category:

8-bit Microcontrollers

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 6194 and 6194.001 Final Notice: Qualification of MTAI as an additional assembly site for selected ATtiny13, ATtiny25 and QT113B device families available in 8L SOIC 3.90mm(.150in) package with MSL 1 classification.

### Affected CPNs:

[LIAL-14KZIS105\\_Affected\\_CPN\\_07042023.pdf](#)

[LIAL-14KZIS105\\_Affected\\_CPN\\_07042023.csv](#)

### Notification Text:

**PCN Status:**Final Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of MTAI as an additional assembly site for selected ATtiny13, ATtiny25 and QT113B device families available in 8L SOIC 3.90mm(.150in) package with MSL 1 classification

### Pre and Post Change Summary:

	Pre change		Post Change		
Assembly Site	Lingsen Precision Industries, LTD. (LPI)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Lingsen Precision Industries, LTD. (LPI)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	Microchip Technology Thailand (HQ) (MTAI)
Wire Material	CuPdAu/Au	Cu / Au	CuPdAu/Au	Cu / Au	Au
Die Attach Material	CRM-1033BF	8290	CRM-1033BF	8290	8390A
Molding Compound Material	G600	G600/G700LS	G600	G600/G700LS	G600V
Lead-Frame Material	C194	C194	C194	C194	CDA194
Lead-Frame Paddle Size	95 x 130 mils	90 x 130 mils/95x155 mils	95 x 130 mils	90 x 130 mils/95x155 mils	90x90mils/ 95x130 mils
DAP Surface Prep	Ag ring plate	Ag ring plate	Ag ring plate	Ag ring plate	Bare Cu
Lead-lock	No	No	No	No	Yes
Lead-Frame Design	See attached pre and post change comparison				
Moisture Sensitivity Level (MSL)	MSL 2	MSL 2	MSL 2	MSL 2	MSL 1

Note: \* C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference”

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**August 26, 2023 (date code: 2334)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	July 2023					August 2023				
Workweek	26	27	28	29	30	31	32	33	34	35

Qual Report Availability		x								
Final PCN Issue Date		x								
Estimated Implementation Date									x	

**Method to Identify Change:**Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:**July 4, 2023: Issued final notification

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

- [PCN\\_LIAL-14KZIS105 Qual Report.pdf](#)
- [PCN\\_LIAL-14KZIS105 Pre and Post Change Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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